



Material Content Data Sheet



Sales Product Name		IFX27001TFV		Issued		25. January 2018		
MA#		MA000724038						
Package		PG-TO252-3-11		Weight*		379.50 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.924	0.77	0.77	7705	7705
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		170	
	non noble metal	iron	7439-89-6	0.215	0.06		567	
	non noble metal	copper	7440-50-8	215.017	56.66	56.74	566581	567318
	non noble metal	aluminium	7429-90-5	0.131	0.03	0.03	344	344
wire	non noble metal	aluminium	7429-90-5	0.131	0.03	0.03	344	344
encapsulation	organic material	carbon black	1333-86-4	0.267	0.07		704	
	plastics	epoxy resin	-	12.286	3.24		32375	
	inorganic material	silicondioxide	60676-86-0	120.992	31.88	35.19	318820	351899
leadfinish	non noble metal	tin	7440-31-5	3.740	0.99	0.99	9855	9855
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	239	240
solder	non noble metal	tin	7440-31-5	0.091	0.02		241	
	noble metal	silver	7440-22-4	0.114	0.03		301	
	non noble metal	lead	7439-92-1	4.363	1.15	1.20	11497	12039
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.05	5.06	50534	50600
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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